

# Sue Ann Bidstrup Allen

## List of Publications by Citations

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37  
papers

822  
citations

15  
h-index

28  
g-index

38  
ext. papers

899  
ext. citations

3.3  
avg, IF

3.34  
L-index

#	Paper	IF	Citations
37	Functionalized polynorbornene dielectric polymers: Adhesion and mechanical properties. <i>Journal of Polymer Science, Part B: Polymer Physics</i> , <b>1999</b> , 37, 3003-3010	2.6	128
36	Fabrication of microchannels using polycarbonates as sacrificial materials. <i>Journal of Micromechanics and Microengineering</i> , <b>2001</b> , 11, 733-737	2	78
35	Biodegradable magnesium/iron batteries with polycaprolactone encapsulation: A microfabricated power source for transient implantable devices. <i>Microsystems and Nanoengineering</i> , <b>2015</b> , 1,	7.7	59
34	Porous Methylsilsesquioxane for Low-k Dielectric Applications. <i>Electrochemical and Solid-State Letters</i> , <b>2001</b> , 4, F25		55
33	Crosslinking and decomposition reactions of epoxide functionalized polynorbornene. Part I. FTIR and thermogravimetric analysis. <i>Journal of Applied Polymer Science</i> , <b>2003</b> , 89, 568-577	2.9	43
32	Chemically Bonded Porogens in Methylsilsesquioxane. <i>Journal of the Electrochemical Society</i> , <b>2002</b> , 149, F161	3.9	43
31	Plasma Treatment and Surface Analysis of Polyimide Films for Electroless Copper Buildup Process. <i>Journal of the Electrochemical Society</i> , <b>2005</b> , 152, F162	3.9	40
30	Improved fabrication of micro air-channels by incorporation of a structural barrier. <i>Journal of Micromechanics and Microengineering</i> , <b>2005</b> , 15, 35-42	2	31
29	Low-Temperature Bonding of Copper Pillars for All-Copper Chip-to-Substrate Interconnections. <i>Electrochemical and Solid-State Letters</i> , <b>2006</b> , 9, C192		30
28	Fabrication of Microchannels Using Polynorbornene Photosensitive Sacrificial Materials. <i>Journal of the Electrochemical Society</i> , <b>2003</b> , 150, H205	3.9	26
27	Chemically Bonded Porogens in Methylsilsesquioxane. <i>Journal of the Electrochemical Society</i> , <b>2002</b> , 149, F171	3.9	23
26	Electroless Deposition of Copper on Organic and Inorganic Substrates Using a Sn/Ag Catalyst. <i>Journal of the Electrochemical Society</i> , <b>2012</b> , 159, D386-D392	3.9	22
25	Photosensitive polynorbornene based dielectric. I. Structure-property relationships. <i>Journal of Applied Polymer Science</i> , <b>2004</b> , 91, 3023-3030	2.9	21
24	Comparison of plasma chemistries and structure-property relationships of fluorocarbon films deposited from octafluorocyclobutane and pentafluoroethane monomers. <i>Journal of Vacuum Science &amp; Technology an Official Journal of the American Vacuum Society B, Microelectronics Processing and Phenomena</i> , <b>2001</b> , 19, 439		18
23	Aqueous-Develop, Photosensitive Polynorbornene Dielectric: Properties and Characterization. <i>Journal of Electronic Materials</i> , <b>2009</b> , 38, 778-786	1.9	16
22	A MEMS-enabled biodegradable battery for powering transient implantable devices <b>2014</b> ,		15
21	Adhesion Enhancement Between Electroless Copper and Epoxy-based Dielectrics. <i>IEEE Transactions on Advanced Packaging</i> , <b>2009</b> , 32, 758-767		15

20	All-Copper Chip-to-Substrate Interconnects Part II. Modeling and Design. <i>Journal of the Electrochemical Society</i> , <b>2008</b> , 155, D314	3.9	15
19	. <i>Journal of Microelectromechanical Systems</i> , <b>2014</b> , 23, 1281-1289	2.5	13
18	Photosensitive polynorbornene based dielectric. II. Sensitivity and spatial resolution. <i>Journal of Applied Polymer Science</i> , <b>2004</b> , 91, 3031-3039	2.9	12
17	Dual capacitor technique for measurement of through-plane modulus of thin polymer films. <i>Journal of Polymer Science, Part B: Polymer Physics</i> , <b>2000</b> , 38, 1634-1644	2.6	12
16	In situ measurement of the thermal expansion behavior of benzocyclobutene films. <i>Journal of Polymer Science, Part B: Polymer Physics</i> , <b>1999</b> , 37, 311-321	2.6	12
15	Air-Gaps for High-Performance On-Chip Interconnect Part I: Improvement in Thermally Decomposable Template. <i>Journal of Electronic Materials</i> , <b>2008</b> , 37, 1524-1533	1.9	11
14	Crosslinking and decomposition reactions of epoxide-functionalized polynorbornene. II. Impact of reactions on mechanical properties. <i>Journal of Applied Polymer Science</i> , <b>2004</b> , 91, 1020-1029	2.9	11
13	Lithographic Characteristics and Thermal Processing of Photosensitive Sacrificial Materials. <i>Journal of the Electrochemical Society</i> , <b>2002</b> , 149, G555	3.9	11
12	Hydrophobic/hydrophilic surface modification within buried air channels. <i>Journal of Vacuum Science &amp; Technology an Official Journal of the American Vacuum Society B, Microelectronics Processing and Phenomena</i> , <b>2004</b> , 22, 953		10
11	Photodefinable Epoxycyclohexyl Polyhedral Oligomeric Silsesquioxane. <i>Journal of Electronic Materials</i> , <b>2010</b> , 39, 149-156	1.9	9
10	Photoinitiation systems and thermal decomposition of photodefinable sacrificial materials. <i>Journal of Applied Polymer Science</i> , <b>2003</b> , 88, 1186-1195	2.9	9
9	UV-induced porosity using photogenerated acids to catalyze the decomposition of sacrificial polymers templated in dielectric films. <i>Journal of Materials Chemistry</i> , <b>2007</b> , 17, 873-885		7
8	Air-Gaps for High-Performance On-Chip Interconnect Part II: Modeling, Fabrication, and Characterization. <i>Journal of Electronic Materials</i> , <b>2008</b> , 37, 1534-1546	1.9	6
7	Model-assisted development of microfabricated 3D Ni(OH) <sub>2</sub> electrodes with rapid charging capabilities. <i>Journal of Power Sources</i> , <b>2017</b> , 358, 101-111	8.9	5
6	Imprint lithography enabling ultra-low loss coaxial interconnects. <i>Microelectronic Engineering</i> , <b>2011</b> , 88, 240-246	2.5	5
5	Electron-beam hardening of thin films of functionalized polynorbornene copolymer. <i>Journal of Electronic Materials</i> , <b>2006</b> , 35, 1112-1121	1.9	4
4	Enhanced photo-patterning of polymer dielectrics via imprint lithography. <i>Microelectronic Engineering</i> , <b>2012</b> , 93, 19-26	2.5	3
3	3D lithium ion battery fabrication via scalable stacked multilayer electrodeposition. <i>Journal of Micromechanics and Microengineering</i> , <b>2019</b> , 29, 055006	2	2

- 2 Vertically integrated high voltage Zn-Air batteries enabled by stacked multilayer electrodeposition. *Journal of Power Sources*, **2020**, 449, 227566 8.9 1
- 1 Functionalized polynorbornene dielectric polymers: Adhesion and mechanical properties **1999**, 37, 3003 1